

Low Power, Low Dropout, RF-Linear Regulators

GENERAL DESCRIPTION

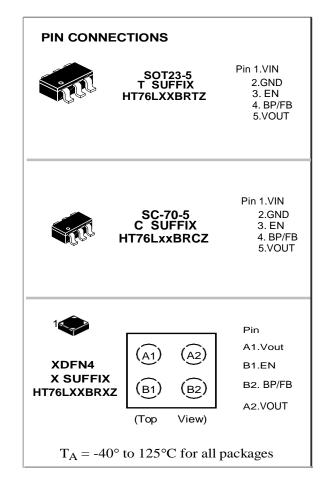
The HT76LxxB series low-power, low-noise, low-dropout, CMOS linear voltage regulators operate from a 2.5V to 5.5V input voltage. They are the perfect choice for low voltage, low power applications. A low ground current makes this part attractive for battery operated power systems. The HT76LxxB series also offer ultra low dropout voltage to prolong battery life in portable electronics. Systems requiring a quiet voltage source, such as RF applications, will benefit from the HT76LxxB series' ultra low output noise $(30\mu V_{RMS})$ and high PSRR. An external noise bypass capacitor connected to the device's BP pin can further reduce the noise level. The output voltage is preset to voltages in the range of 1.2V to 5.0V. Other features include a 10nA logic-controlled shutdown mode, foldback current limit and thermal shutdown protection. The HT76LxxB is available in Green SOT-23-5 and SC70-5 packages. It operates over an ambient temperature range of -40°C to +85°C.

FEATURES

- Low Output Noise
- Low Dropout Voltage
- Thermal-Overload Protection
- Output Current Limit
- High PSRR (74dB at 1kHz)
- 10nA Logic-Controlled Shutdown
- Available in Multiple Output Voltage Versions
- Fixed Outputs of 1.2V, 1.5V, 1.8V, 2.5V, 2.6V, 2.8V, 2.85V, 3.0V and 3.3V
- Adjustable Output from 1.2V to 5.0V
- -40°C to +85°C Operating Temperature Range
- Available in Green SC70-5 and SOT-23-5 Packages

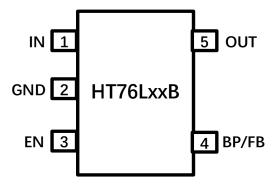
APPLICATIONS

Cellular Telephones Cordless Telephones PCMCIA Cards Modems MP3 Player Hand-Held Instruments Palmtop Computers Electronic Planners Portable/Battery-Powered Equipment





PIN CONFIGURATIONS(TOP VIEW)



NOTES:

1. The location of pin 1 on the RExx is determined by orienting the package marking as shown.

2. "xx" is the output voltage code. (For Example: when the output voltage is 1.8V, it is expressed as 18.)

NOTE:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ABSOLUTE MAXIMUM RATINGS

IN to GND0.3V to 6V
Output Short-Circuit DurationInfinite
EN to GND0.3V to VIN
OUT, BP/FB to GND0.3V to (VIN + 0.3V)
Power Dissipation, PD @ TA = 25°C
SOT-23-50.4W
SC70-50.3W
Package Thermal Resistance
SOT-23-5,θ _{JA}
SC70-5,θ _{JA} 330°C/W
Operating Temperature Range40℃ to +85℃
Junction Temperature 150°C
Storage Temperature Range65℃ to +150℃
Lead Temperature (Soldering, 10s)260°C
ESD Susceptibility
HBM2000V
MM



PIN DESCRIPTION

PIN		FUNCTION		
SC70-5/SOT-23-5	NAME	FUNCTION		
1	IN	Regulator Input. Supply voltage can range from 2.5V to 5.5V. Bypass with a 1 μ F capacitor to GND.		
2	GND	Ground.		
3	EN	Shutdown Input. A logic low reduces the supply current to 10nA. Connect to IN for normal operation.		
4	ВР	Reference-Noise Bypass (fixed voltage version only). Bypass with a low-leakage 0.01μ F ceramic capacitor for reduced noise at the output.		
	FB	Adjustable Voltage Version Only. This is used to set the output voltage of the device.		
5	OUT	Regulator Output.		



ELECTRICAL CHARACTERISTICS

(V_{IN} = V_{OUT (NOMINAL)} + 0.5V $^{(1)}$, Full = -40°C to +85°C, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS		TEMP	MIN	TYP	MAX	UNITS
Input Voltage	V _{IN}			+25°C	2.5		5.5	V
Output Voltage Accuracy (1)		I _{OUT} = 0.1mA		+25°C	-2.5		2.5	%
		SOT-23-5			300			
Maximum Output Current ⁽¹⁾		V _{OUT} = 1.2V, 1.5V, 1.8V, SC70-5 V _{OUT} > 2V, SC70-5		+25°C	150			mA
					250			
Current Limit (1)	I _{LIM}			+25°C	310	500		mA
Ground Pin Current	Ι _Q	No load, EN = 2V		+25°C		100	200	μA
Dropout Voltage (2)		I _{OUT} = 1mA I _{OUT} = 300mA		+25°C		0.9		mV
Dropout voltage						270	400	
Line Regulation (1)	ΔV_{LNR}	V _{IN} = 2.5V or (V _{OUT} + 0.5V) to 5.5V, I _{OUT} = 1mA		+25°C		0.02	0.05	%/V
Lead Devideffer	ΔV_{LDR}	I_{OUT} =0.1mA to 300mA, C_{OUT} = 1µF, V _{OUT} > 2V		+25°C		0.002	0.005	%/mA
Load Regulation		I_{OUT} =0.1mA to 300mA, C_{OUT} = 1µF, V _{OUT} ≤ 2V				0.004	0.008	
Output Voltage Noise	en	$f = 10Hz$ to 100kHz, $C_{BP} = 0.01\mu F$, $C_{OUT} = 10\mu F$		+25°C		30		μV_{RMS}
	5055	$C_{BP} = 0.1 \mu F$, $I_{LOAD} = 50 m A$,	f = 217Hz	+25°C		77		dB
Power Supply Rejection Ratio	PSRR	$C_{OUT} = 1\mu F$, $V_{IN} = V_{OUT} + 1V$	f = 1kHz	+25°C		74		dB
SHUTDOWN ⁽³⁾		I		1				
EN Innut Threshold			2V/to V/	Full	1.5			V
EN Input Threshold	VIL	$V_{IN} = 2.5V$ to 5.5V, $V_{EN} = -0.3$	5V (O V _{IN}	Full		0.3 V	v	
EN Input Bias Current		EN = 0V or EN = 5.5V		+25°C		0.01	1	
EN INPUL DIAS CUITERIL	I _{B(SHDN)}	EIN = 0V OI EIN = 5.5V		Full		0.01		μA
Shutdown Supply Current	I _{Q(SHDN)}	EN = 0.4V		Full		0.01		μA
Shutdown Exit Delay (4)		C_{BP} = 0.01µF, C_{OUT} = 1µF, No Load		+25°C		30		μs
THERMAL PROTECTION	•	•					•	
Thermal Shutdown Temperature	T _{SHDN}					150		°C
Thermal Shutdown Hysteresis	ΔT_{SHDN}					15		°C

NOTES:

1. $V_{IN} = V_{OUT (NOMINAL)} + 0.5V$ or 2.5V, whichever is greater.

2. The dropout voltage is defined as V_{IN} - V_{OUT} , when V_{OUT} is 100mV below the value of V_{OUT} for V_{IN} = V_{OUT} + 0.5V.

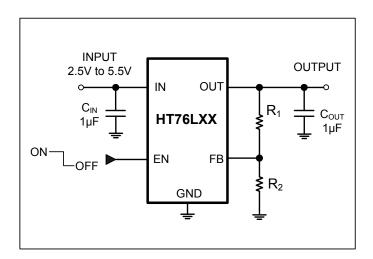
(Only applicable for V_{OUT} = +2.5V to +5.0V.)

3. V_{EN} = -0.3V to V_{IN}

4. Time needed for V_{OUT} to reach 90% of final value.



TYPICAL APPLICATION CIRCUIT

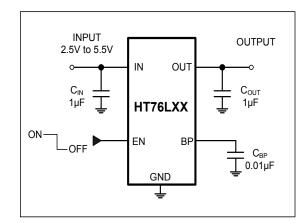


V _{OUT} (V)	R ₁ (kΩ)	R ₂ (kΩ)
1.2	0	63.4
1.5	10.5	42.2
1.8	34	63.4
2.8	84.5	63.4
3.0	63.4	42.2
3.3	73.2	42.2
3.6	84.5	42.2
4.2	105	42.2

NOTE: V_{OUT} = (R₁ + R₂)/ R₂ × 1.207



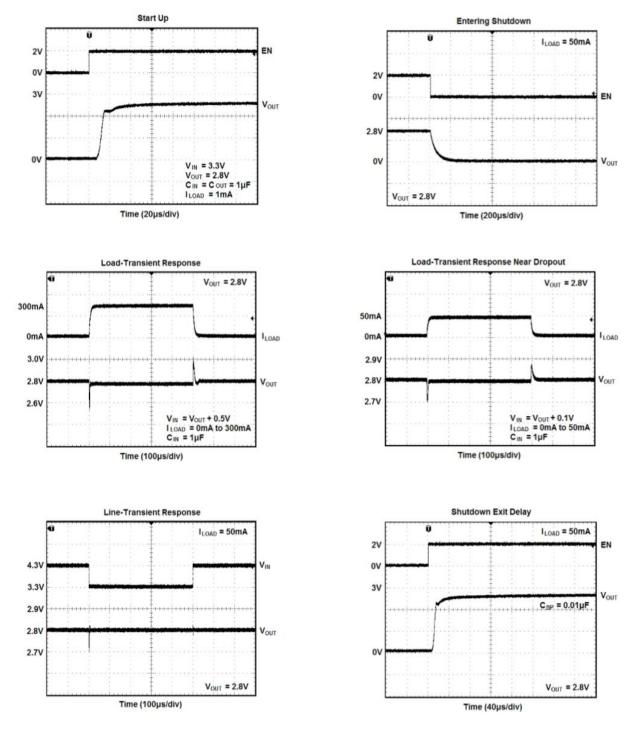
TYPICAL APPLICATION CIRCUIT



С _{вР} (nF)	Shutdown Exit Delay (μs) V _{OUT} = 2.8V, V _{IN} = 3.3V, EN = 0V to 2V			PSRR (dB) at 217Hz V _{OUT} = 2.8V, V _{IN} = V _{OUT} + 1V			
	I _{LOAD} = 50mA	I _{LOAD} = 150mA	I _{LOAD} = 300mA	I _{LOAD} = 50mA	I _{LOAD} = 150mA	I _{LOAD} = 300mA	
None	21.5	21.5	21	71.1	64.4	55.0	
0.001	21.5	21.5	22	71.1	64.6	55.1	
0.01	22	22.5	22.5	71.6	64.7	55.2	
0.1	22.5	23	23	71.7	64.8	55.4	
1	25	27	28.5	72.1	65.2	55.9	
10	30	35	39	74.3	68.8	59.6	
100	265	280	300	77.0	73.7	63.1	

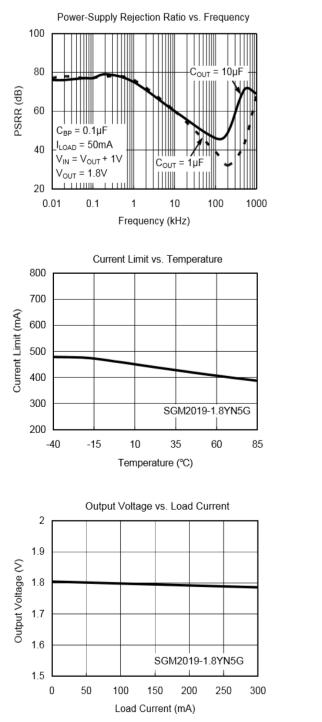


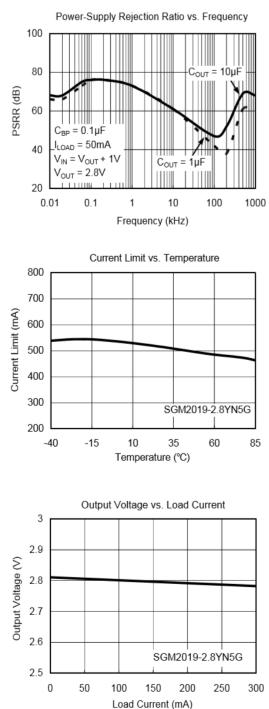
 $V_{IN}=V_{OUT(NOMINAL)}+0.5V$ or 2.5V(whichever is greater), $C_{IN}=1\mu F$, $C_{OUT}=1\mu F$, $C_{BP}=0.01\mu F$, $T_{A}=+25^{\circ}C$, unless otherwise noted.





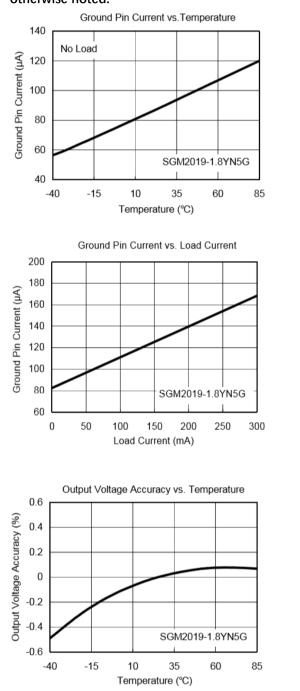
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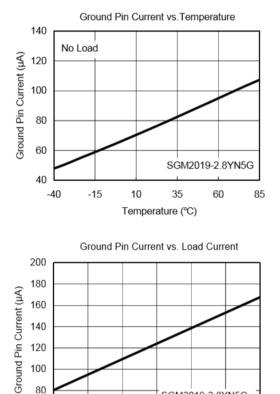


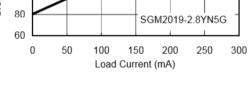


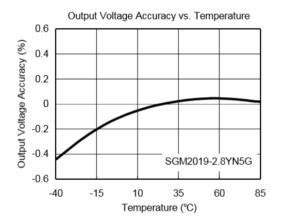


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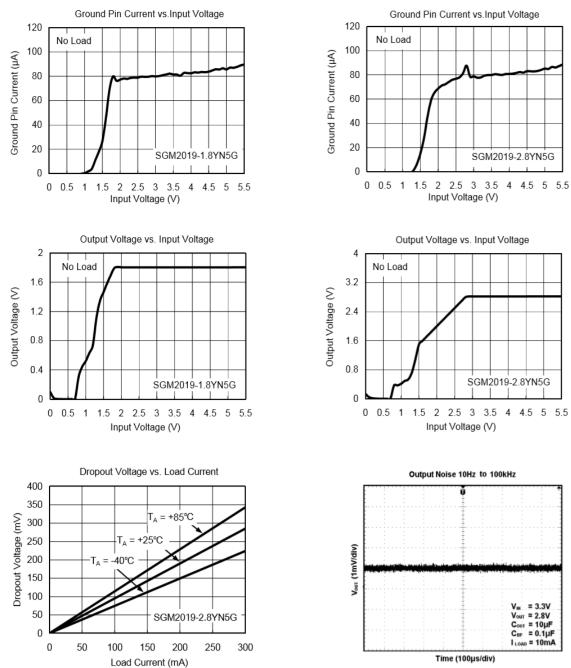






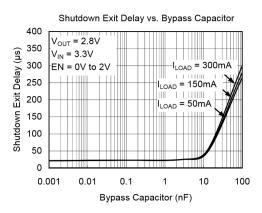


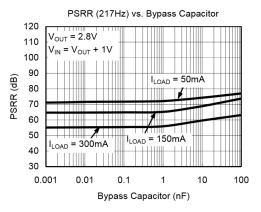
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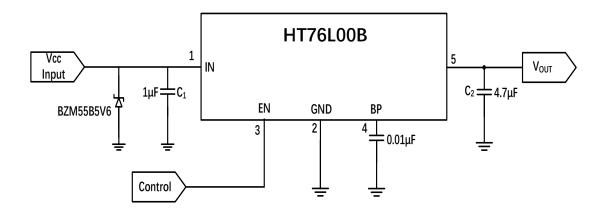






APPLICATION NOTE

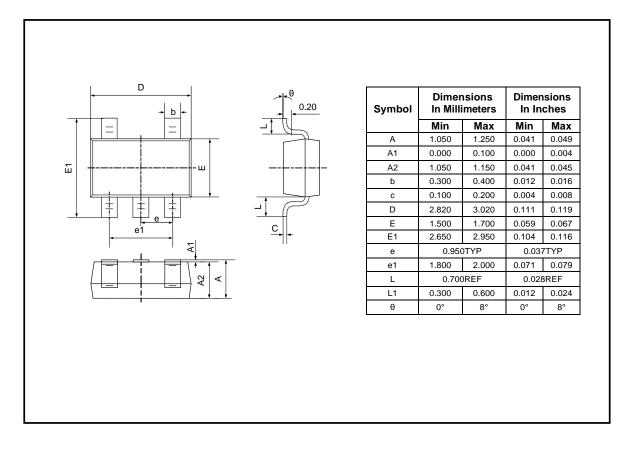
When LDO is used in handheld products, attention must be paid to voltage spikes which could damage HT76LxxB. In such applications, voltage spikes will be generated at charger interface and VBUS pin of USB interface when charger adapters and USB equipments are hot-plugged. Besides this, handheld products will be tested on the production line without battery. Test engineer will apply power from the connector pin which connects with positive pole of the battery. When external power supply is turned on suddenly, the voltage spikes will be generated at the battery connector. The voltage spikes will be very high, and it always exceeds the absolute maximum input voltage (6.0V) of LDO. In order to get robust design, design engineer needs to clear up this voltage spike. Zener diode is a cheap and effective solution to eliminate such voltage spike. For example, BZM55B5V6 is a 5.6V small package Zener diode which can be used to remove voltage spikes in cell phone designs. The schematic is shown below.





PACKAGE OUTLINE DIMENSIONS

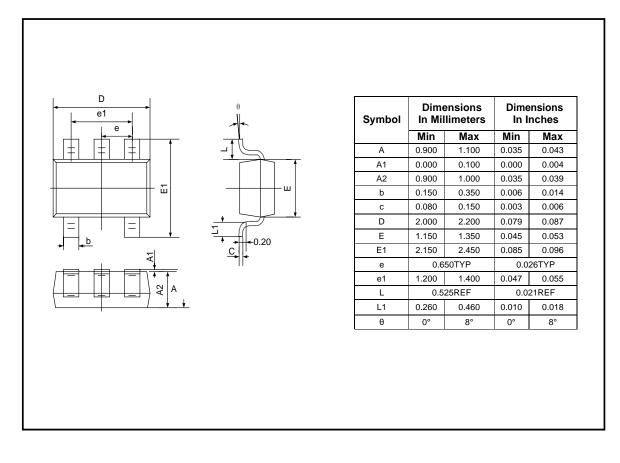
SOT23-5





PACKAGE OUTLINE DIMENSIONS

SC70-5



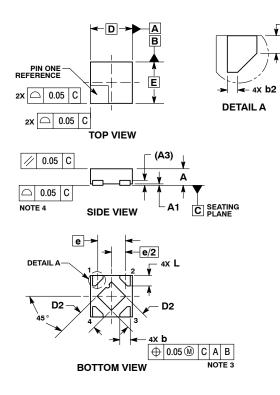




PACKAGE DIMENSIONS

XDFN4 1.0x1.0, 0.65P X SUFFIX

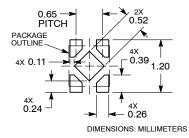
4X L2



- NOTES: 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS. 3. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 mm FROM THE TERMINAL TIPS. 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS			
DIM	MIN	MAX		
Α	0.33	0.43		
A1	0.00	0.05		
A3	0.10 REF			
b	0.15	0.25		
b2	0.02	0.12		
D	1.00 BSC			
D2	0.43	0.53		
Е	1.00	1.00 BSC		
е	0.65 BSC			
L	0.20	0.30		
L2	0.07	0.17		

RECOMMENDED MOUNTING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.